

## Preface

ICNFCM2017 aims to present the latest research and results of scientists (academicians, PhD Students and engineers) related to the science and technology of Nano-materials including Multifunctional Composite Materials, Polymers, Ceramics and Functional materials. This conference provides opportunities for the different areas delegates to exchange new ideas and application experiences face to face, to establish business or research relations and to find global partners for future collaboration.

All papers were accepted through a peer-review process by the conference program committee and international reviewers. The selected papers contributions to be presented as lectures will make an exciting technical program. And the conference program is extremely rich, featuring high-impact presentation. We hope that the conference results constituted significant contribution to the knowledge in these up to date scientific field.

Finally, we wish all the authors and attendees of ICNFCM2017 a unique, rewarding and enjoyable memory at ICNFCM2017 in Hong Kong. We look forward to your participation in the 2<sup>nd</sup> ICNFCN 2018 in 2018.

With our warmest regards,

Conference Organizing Chair

Hariati Taib

Universiti Tun Hussein Onn Malaysia

July 2017

# Committees

## Conference Secretary

Sherry Chen, BOSI Education & Consultancy, China

## Program Committee

Prof. Mieczyslaw Lapkowski, Silesian University of Technology, Poland

Prof. Mahmoud Pakshir, Shiraz University, Iran

Prof. Farid Abed-Meraim, Arts et Métiers ParisTech, Metz, France

Prof. Changguo Wang, Center for Composite Materials/School of Astronautics, Harbin Institute of Technology (HIT), China

Dr. Hassan Abdollah-Pour, University of Semnan, Semnan, Iran

Assoc. Prof. PhD. Eng. Stefan Talu, The Technical University of Cluj-Napoca, Romania

Dr. Khaled Habib, Materials Science and Photo-Electronics Lab., RE Program, EBR Center KISR, Kuwait

Prof. Elias Stathatos, Technological-Educational Institute of Western Greece, Greece

Prof. Saulius Grigalevicius, Kaunas University of Technology, Lithuania

Dr. K.R. Venugopala Reddy, Jnana Sagara Vijayanagara Sri Krishnadevaraya University, India

Dr. Ram Gupta, Pittsburg State University, KS, USA

Dr. Phang Sook Wai, Tunku Abdul Rahman University College, Malaysia

Prof. Yingquan Peng, China Jiliang University

Prof. Honey John, Cochin University of Science and Technology, Kochi, India

Dr. Jagriti Narang, Amity University, Noida (U.P), India

Prof. Ali Bahari Panbehchooleh, The University of Mazandaran (UMZ), Iran

Prof. Cesar Alfredo Barbero, National University of Rio Cuarto, Argentina

Asso Prof. Ali Maleki, Iran University of Science and Technology (IUST), Iran

Prof. Mihaela Ghelmez, "Politehnica" University of Bucharest, Romania

Prof. Amitabha De, Saha Institute of Nuclear Physics, Kolkata, India

Assoc. Prof. Moola Mohan Reddy, Curtin University, Malaysia

Dr. Ernie Suzana Binti Ali, Universiti Sains Islam Malaysia, Malaysia

Dr. Mohd Hasmizam Razali, Universiti Malaysia Terengganu (UMT), Malaysia

Dr. Mohammad Reza/Nategghi, Azad University Yazd, Iran

Assoc. Prof. Anika Zafiah Binti Mohd Rus, University Tun Hussein Onn Malaysia, Malaysia

Dr. Nurul Akmal Bt Che Lah, Universiti Malaysia Pahang, Malaysia

Assoc. Prof. Dr. Hariati Taib, Universiti Tun Hussein Onn Malaysia, Malaysia

Engr. Dr. Kumaran a/l Kadirgama, Universiti Malaysia Pahang (UMP), Malaysia

Assist. Prof. Chandrakant Kumar Nirala, The LNM Institute of Information Technology Jaipur, India

Dr. Mohd Ruzaimi Bin Mat Rejab, Universiti Malaysia Pahang (UMP), Malaysia

Dr. Sophia C. Alih, Universiti Teknologi Malaysia, Johor Bahru, Malaysia

Dr. Dandi Bachtiar, Universiti Malaysia Pahang, Malaysia

# **Sponsor**

## **BOSI Education & Consultancy Co, Ltd**

BOSI Education & Consultancy Co, Ltd dedicates to organize worldwide academic conference. BOSI cooperate with IEEE (Institute of Electrical and Electronics Engineers), IEEE Harbin (Dalian) Section CIS Chapter and top university from in and out China by arranging and holding slap-up conferences on electrical engineering and automation, computer science, information technology, mechanic, materials, manufacturing engineering etc.. It creates and offers opportunities for experts, researchers and scholars from all over the world to present their technological advances and research results.